MA6X129 (MA129)

Silicon epitaxial planar type

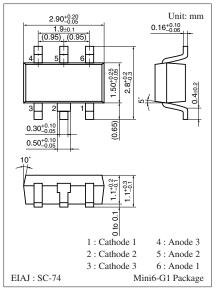
For small power current rectification

Features

- Three isolated elements are contained in one package, allowing high-density mounting
- Allowing high voltage rectification

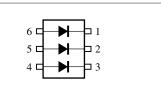
Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter		Symbol	Rating	Unit
Reverse voltage		V _R	200	V
Maximum peak reverse voltage		V _{RM}	200	V
Output current	Single	Io	200	mA
	Triple		100	
Repetitive peak forward	Single	I _{FRM}	600	mA
current	Triple		200	
Non-repetitive peak	Single	I _{FSM}	1 000	mA
forward surge current *	Triple		350	
Junction temperature		Tj	150	°C
Storage temperature		T _{stg}	-55 ~ +150	°C



Marking Symbol: M4F

Internal Connection



Note)	*:	t =	I	s	

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

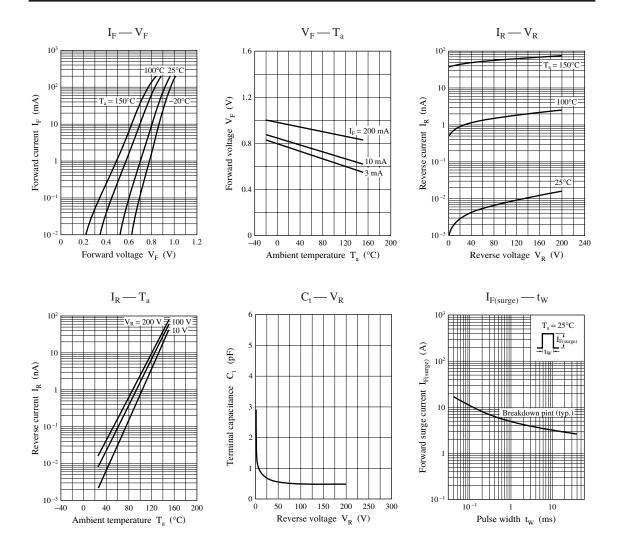
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 200 \text{ mA}$			1.2	V
Reverse current	I _R	$V_{R} = 200 V$			200	nA
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		4.5		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 3 MHz.

Note) The part number in the parenthesis shows conventional part number.

Panasonic



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